



US007012463B2

(12) **United States Patent**
Nairn

(10) **Patent No.:** **US 7,012,463 B2**
(45) **Date of Patent:** **Mar. 14, 2006**

(54) **SWITCHED CAPACITOR CIRCUIT WITH REDUCED COMMON-MODE VARIATIONS**

(75) Inventor: **David G. Nairn**, Greensboro, NC (US)
(73) Assignee: **Analog Devices, Inc.**, Norwood, MA (US)

(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 185 days.

(21) Appl. No.: **10/745,756**

(22) Filed: **Dec. 23, 2003**

(65) **Prior Publication Data**

US 2005/0134380 A1 Jun. 23, 2005

(51) **Int. Cl.**
H03F 3/45 (2006.01)

(52) **U.S. Cl.** **330/9; 330/258; 330/259**

(58) **Field of Classification Search** **330/9, 330/258, 259; 327/124, 307, 563**

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

5,838,200 A *	11/1998	Opris	330/258
6,285,311 B1	9/2001	Lewicki	341/172
6,362,682 B1	3/2002	Shulman	327/562
6,400,301 B1	6/2002	Kulhalli	341/155
6,577,184 B1	6/2003	Kwan	330/9
6,750,715 B1 *	6/2004	Allott et al.	330/258

OTHER PUBLICATIONS

David Johns and Ken Martin, Analog Integrated Circuit Design, 1997, pp. 287-291.

* cited by examiner

Primary Examiner—Steven J. Mottola

(74) *Attorney, Agent, or Firm*—Koppel, Jacobs, Patrick & Heybl

(57) **ABSTRACT**

A circuit with a common-mode dual output includes a feedback circuit connected to alternate the states of the dual output between an average output level and a desired common-mode level. The difference between the average and desired levels is proportional to a signal offset level. An impedance matching circuit is connected to the feedback circuit to adjust the signal offset level.

29 Claims, 6 Drawing Sheets

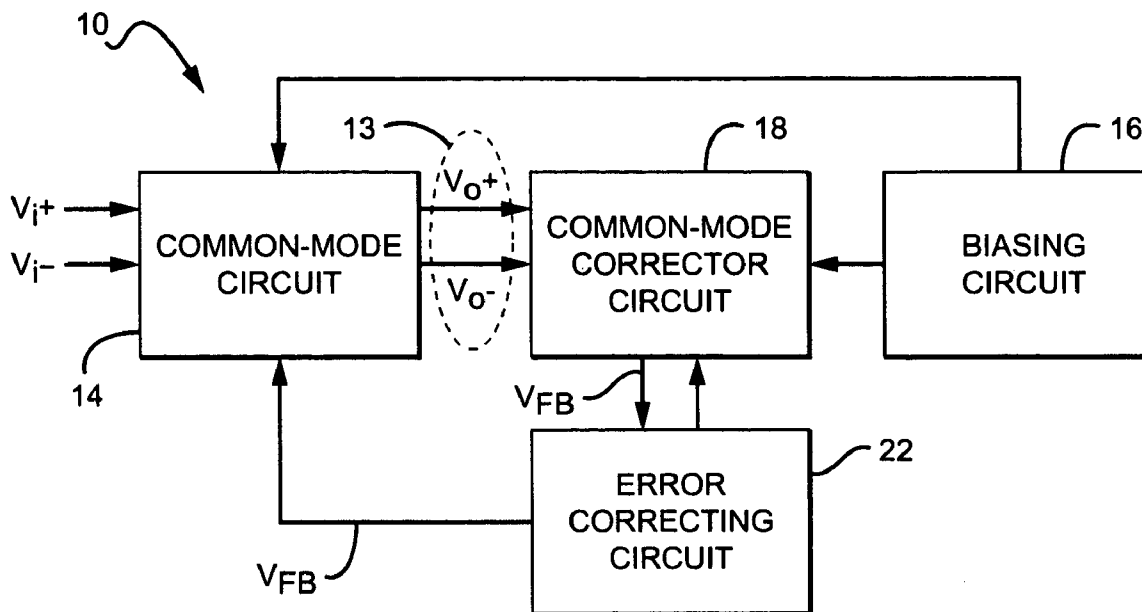


FIG. 1

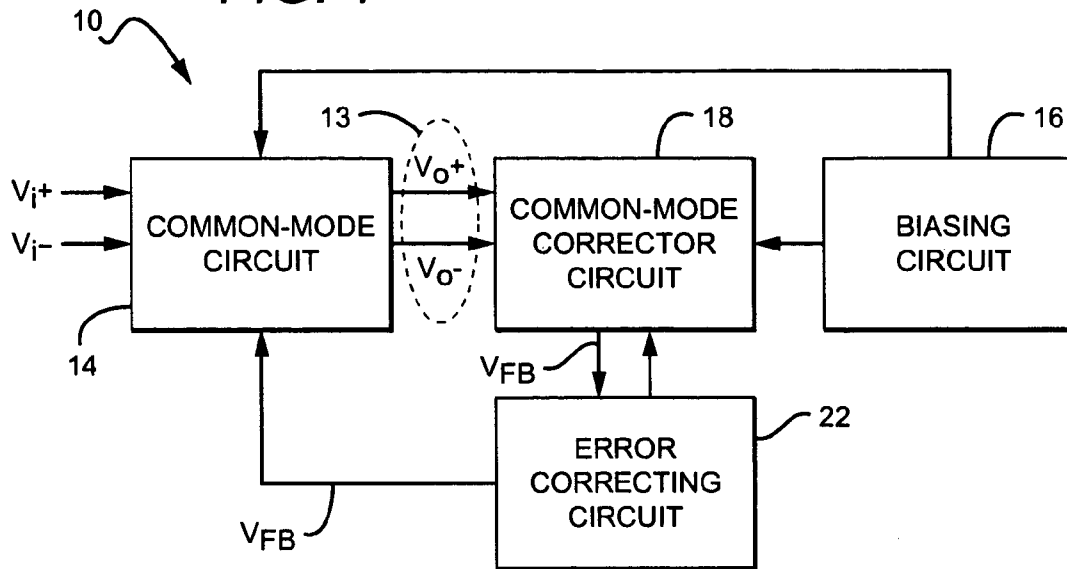
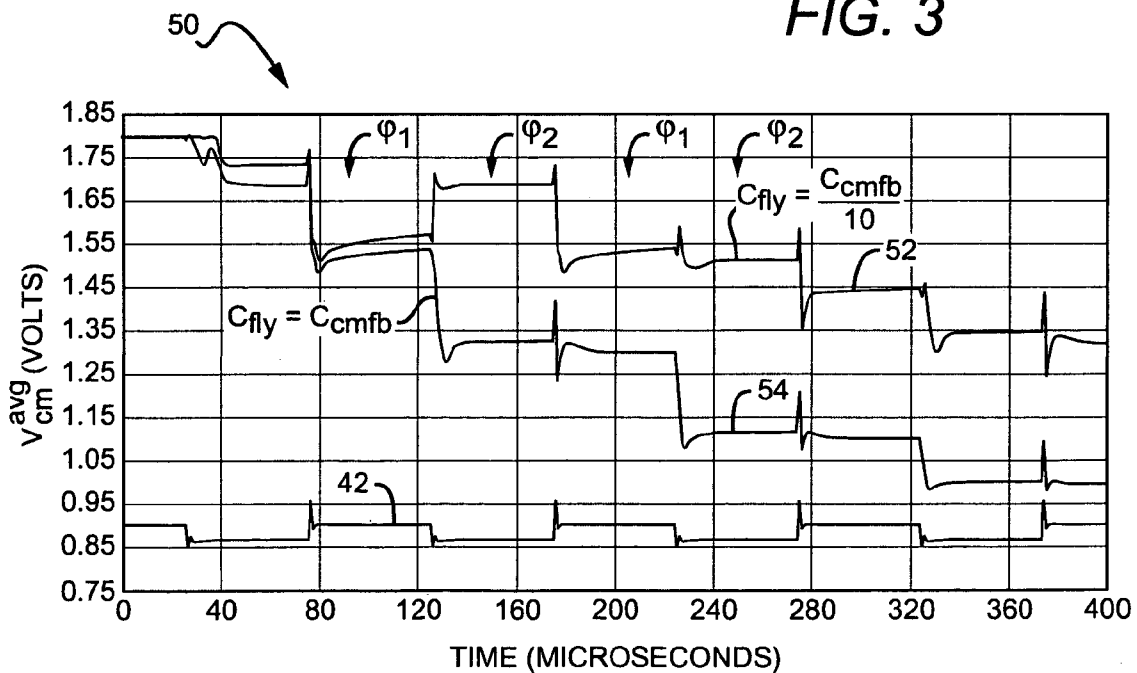


FIG. 3



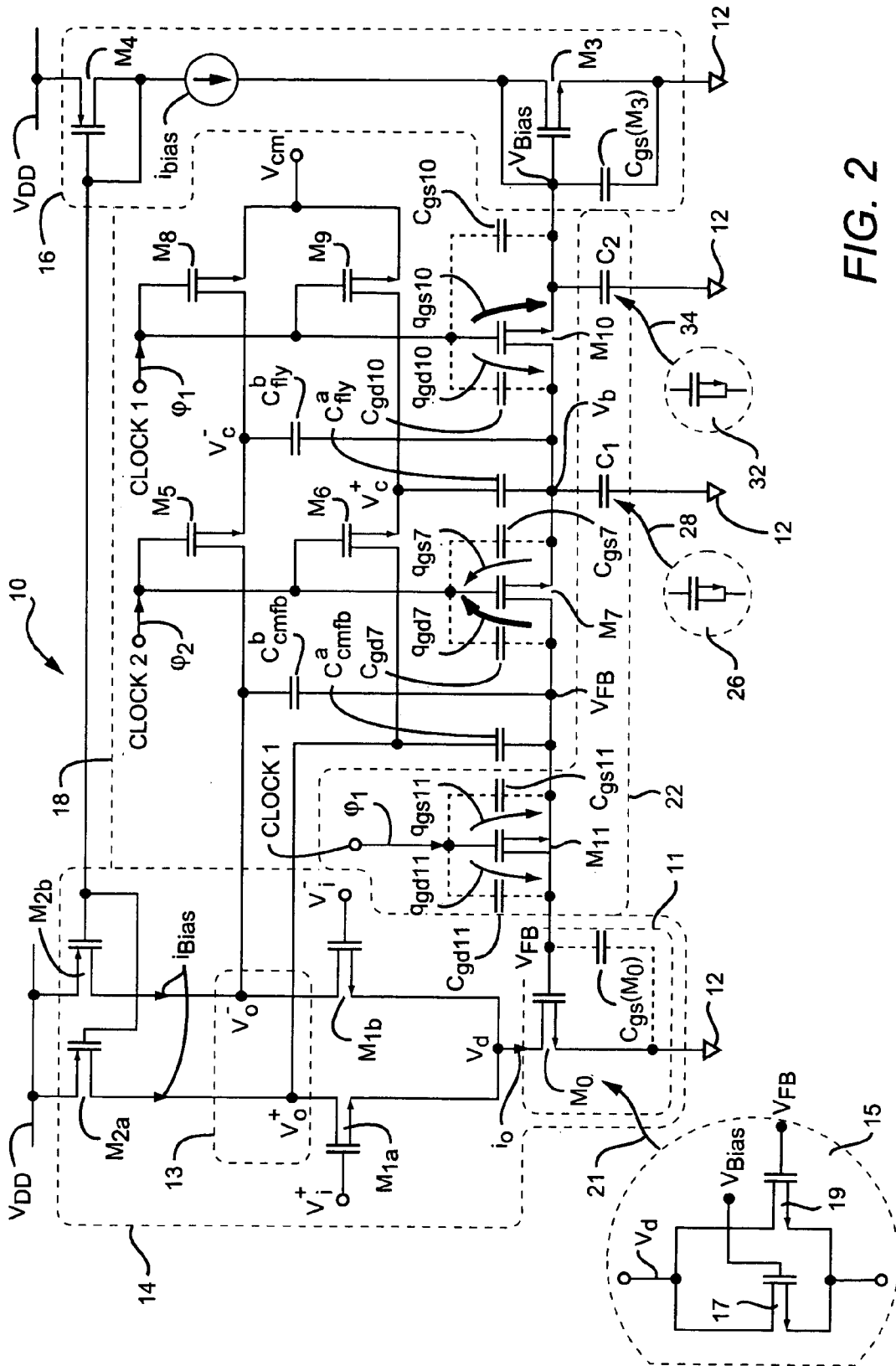
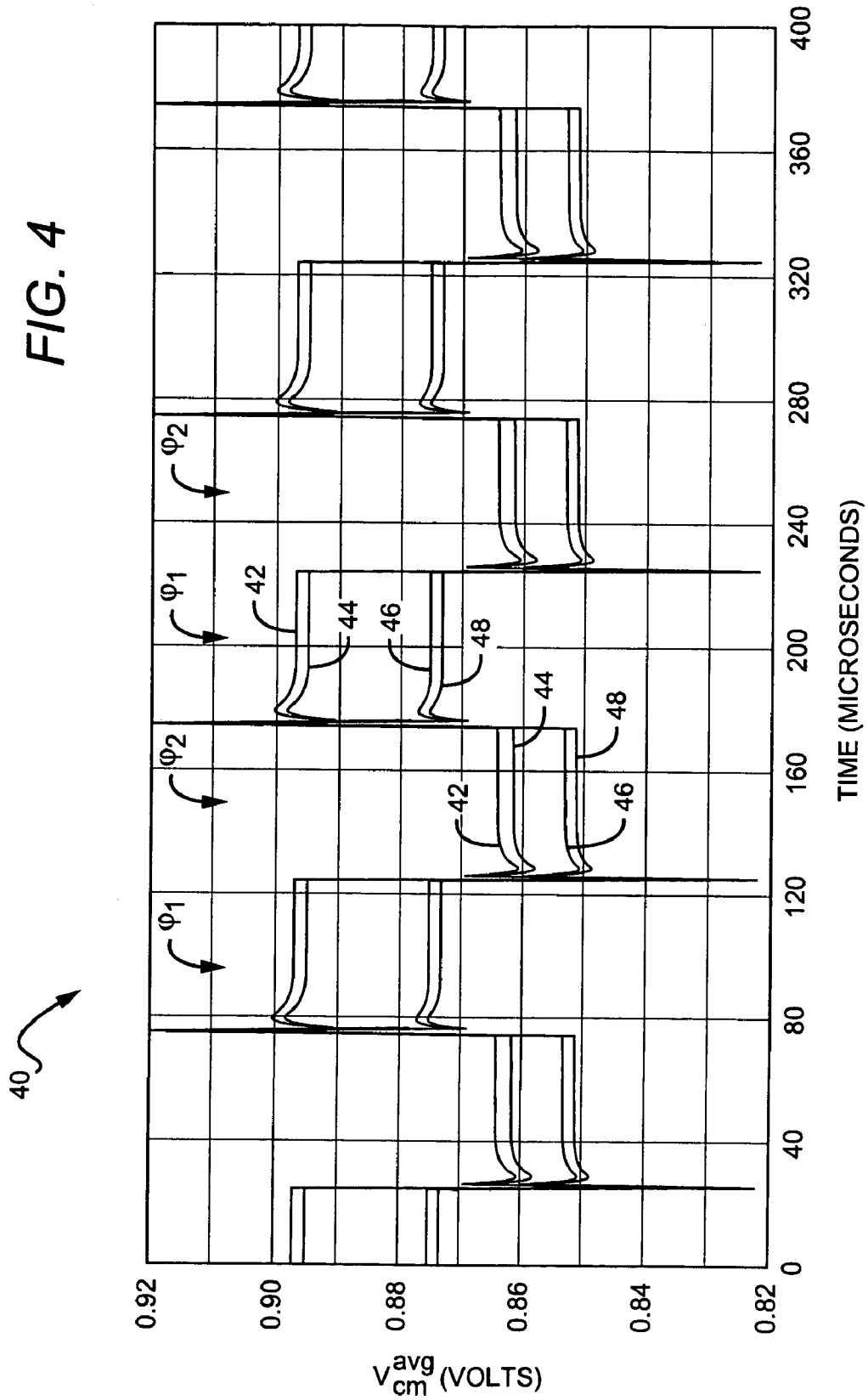


FIG. 2

FIG. 4



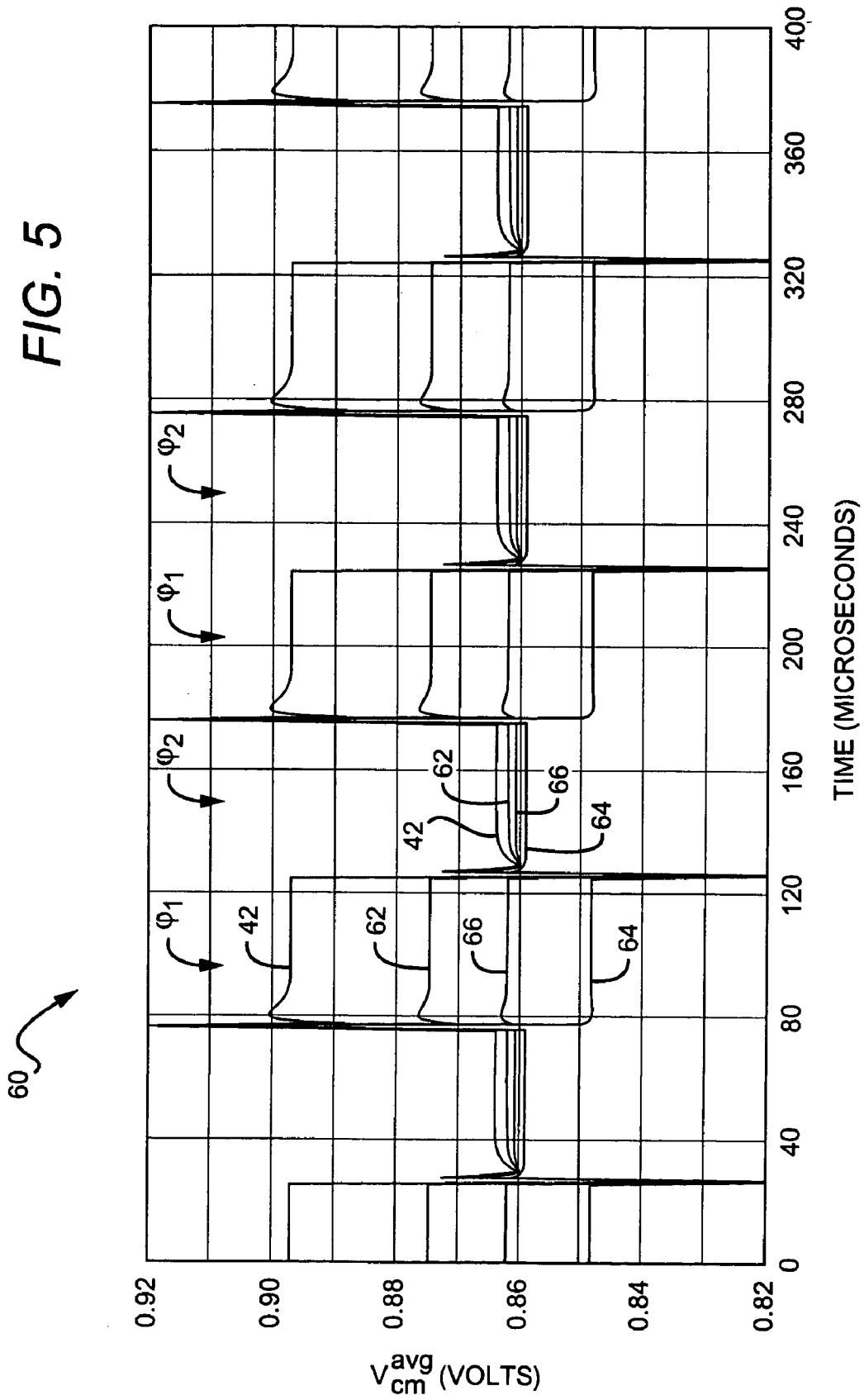


FIG. 6

80 ↗

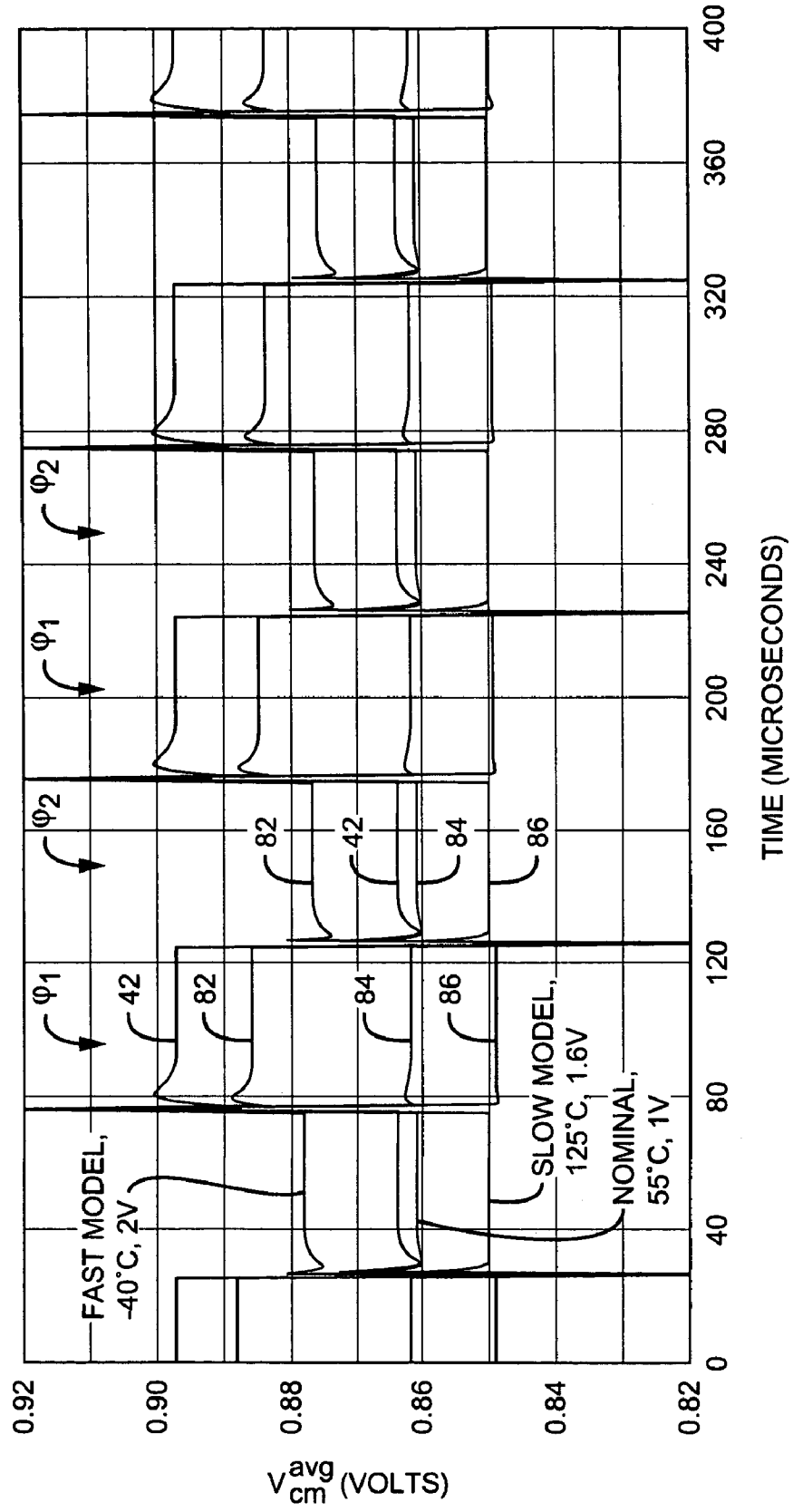
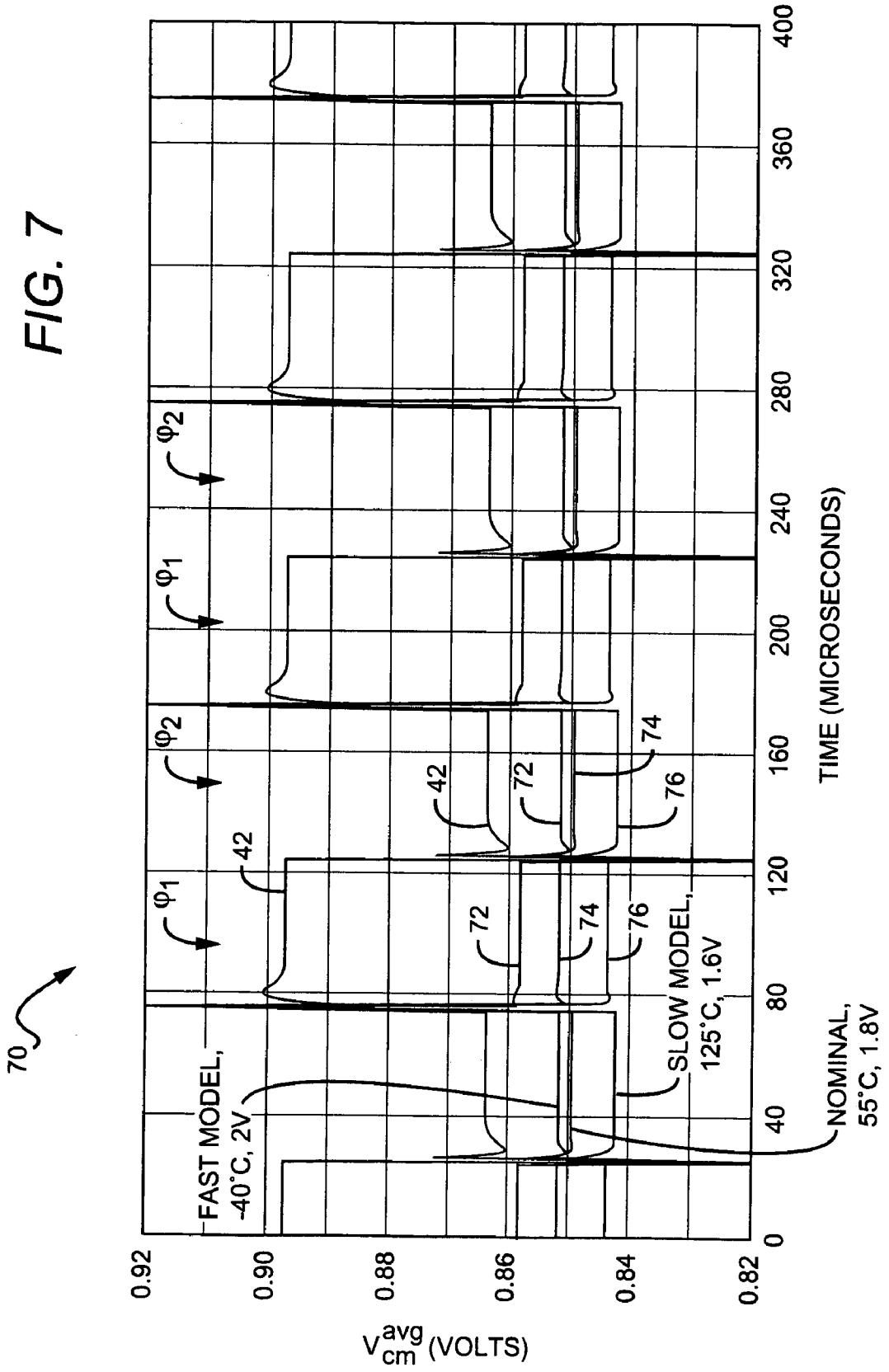


FIG. 7



SWITCHED CAPACITOR CIRCUIT WITH REDUCED COMMON-MODE VARIATIONS

BACKGROUND OF THE INVENTION

1. Field of the Invention

This invention relates generally to electronic circuits and, more particularly, to electronic circuits which include switched capacitor circuitry.

2. Description of the Related Art

For high performance signal conditioning systems, most analog circuits use dual output differential amplifiers. Differential amplifiers amplify the difference between positive and negative input signals and allow the rejection of noise from the substrate and clock signals coupled to the amplifier. However, differential amplifiers also amplify the average of the positive and negative input signals which is generally referred to as the common-mode.

The common-mode limits the common-mode rejection ratio (CMRR) which is defined as the ratio of the differential mode gain to the common-mode gain. Hence, the CMRR can be increased by decreasing the common-mode gain. In differential amplifiers, the common-mode gain can be reduced by including a common-mode feedback loop. In some differential amplifiers, the feedback loop can include switched capacitor circuits as disclosed in U.S. Pat. No. 6,400,301 or as disclosed in D. A. Johns and K. Martin, Analog Integrated Circuit Design, John Wiley and Sons, New York, 1997, Pgs 287–291.

Switched capacitor circuits typically include a number of switches coupled to capacitors where the switches are configured to alternately store and transfer charge between the capacitors. When the switched capacitor circuit is coupled to the differential amplifier, the capacitors can sense the average or common-mode of the output and then compare the average with a desired common-mode. The difference between the average common-mode and the desired common-mode can be used in a feedback loop which drives the difference to zero.

The switches are designed to alternate between two phases or operational modes to control the amplification of the input signals. In some applications, the amplifier is active during a first phase so the common-mode in a second phase is not as critical. However, it may still be desired to control the common-mode during both phases for several reasons. One reason is that the common-mode in the second phase should settle to the common-mode in the first phase to minimize any delays.

Another reason is that in some applications, both the first and second phases are used to amplify the signal. This is often referred to as “amplifier sharing” where it is desired to have the same common-mode for both phases so that the amplification is constant. Hence, it is desired to have the same common-mode when switching between phases to minimize the dependence of the output signal on the common-mode.

The common-mode level at the amplifier’s output can vary due to changes in the common-mode feedback circuit. Small errors within the common-mode feedback circuit are multiplied by the common-mode error gain to provide a common-mode error that varies from one clock phase to the next. These common-mode variations reduce the available signal range for differential amplifiers which is further reduced as circuit supply voltages are reduced. Hence, the common-mode and the common-mode error gain are a concern for low power and portable electronic applications.

BRIEF SUMMARY OF THE INVENTION

In one aspect of the present invention, a circuit with a common-mode dual output includes a common-mode circuit with an output portion. A common-mode corrector circuit is connected to alternate the states of the output portion between an average output level and a desired common-mode level. The difference between the average output level and the desired common-mode level is proportional to a signal offset level. An error correcting circuit is connected to the common-mode corrector circuit to adjust the signal offset level.

In another aspect of the present invention, an integrated circuit includes a differential amplifier circuit with an output portion and a current sinking portion. The output portion includes dual outputs which provide an average output level. A common-mode feedback circuit is coupled to the output portion to provide a desired common-mode level in a first operational mode and generates a feedback signal proportional to the difference between the average output level and the desired common-mode level in a second operational mode. The feedback signal is coupled to the current sinking portion. An impedance matching circuit is connected to the feedback circuit to adjust the feedback signal.

In other aspects of the present invention, a switched capacitor amplifier provides an output signal in response to an input signal and corrects the average output level of the output signal in accordance with a desired common-mode level. The switched capacitor amplifier includes a differential amplifier with an output portion and a current sinking portion where the output portion provides the output signal. A switched capacitor common-mode feedback circuit is coupled between the output portion and the current sinking portion where the feedback circuit is configured to alternate the states of the output portion between the average output level on a precharging capacitor and the desired common-mode level on a common-mode feedback capacitor in response to alternating clock cycles. The difference between the average and desired levels is proportional to a signal offset level. An impedance matching circuit is coupled to the feedback circuit to reduce the signal offset level. The impedance matching circuit includes a charge balancing switch configured to reduce feedthrough between the differential amplifier and the feedback circuit.

These and other features, aspects, and advantages of the present invention will become better understood with reference to the following drawings, description, and claims.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a simplified block diagram of a signal conditioning system in accordance with the present invention;

FIG. 2 is a simplified circuit schematic diagram of the signal conditioning system illustrated in FIG. 1;

FIG. 3 is a graph illustrating a common-mode signal of the circuit illustrated in FIG. 2 as a function of time for capacitances c_{fy}^a and c_{fy}^b equal to $c_{cmfb}^a/10$ and $c_{cmfb}^b/10$, respectively, and capacitances c_{fy}^a and c_{fy}^b equal to c_{cmfb}^a and c_{cmfb}^b , respectively.

FIG. 4 is a graph illustrating the common-mode signal of the circuit illustrated in FIG. 2 as a function of time for different configurations of capacitors C_1 and C_2 ;

FIG. 5 is a graph illustrating the common-mode signal of the circuit illustrated in FIG. 2 as a function of time for different configurations of switch M_{11} ;

FIG. 6 is a graph illustrating the common-mode signal of the circuit illustrated in FIG. 2 as a function of time for

different processing, power supply, and temperature conditions where switch M_{11} , is three-quarters sized and the circuit excludes capacitors C_1 and C_2 ; and

FIG. 7 is a graph illustrating the common-mode signal of the circuit illustrated in FIG. 2 as a function of time for different processing, power supply, and temperature conditions where switch M_{11} , is one-half sized and the circuit includes capacitors C_1 and C_2 .

DETAILED DESCRIPTION OF THE INVENTION

FIG. 1 illustrates a simplified block diagram of a signal conditioning system **10** in accordance with the present invention. System **10** can be included in a signal conditioning system such as an operational amplifier, an analog to digital converter, a digital to analog converter, or a similar circuit where it is desired to amplify the difference between two signals.

In one embodiment, system **10** includes a common-mode circuit **14** coupled to a common-mode corrector circuit **18** through an output port **13**. Circuit **14** is also coupled to common-mode corrector circuit **18** through an error correcting circuit **22**. A biasing circuit **16** is coupled to common-mode circuit **14** and common-mode corrector circuit **18** to provide power and to set an operating point for common-mode circuit **14**.

Port **13** includes differential output terminals V_o^+ and V_o^- which provide respective differential output signals v_o^+ and v_o^- in response to differential input signals v_i^+ and v_i^- at terminals V_i^+ and V_o^- . It should be noted that here and in the following discussion, a physical terminal or component included in system **10** will be indicated with a capital letter and a signal or a measurable value will be indicated with a lower case letter. For example, the differential output terminals are referred to as V_o^+ and V_o^- while signals at the respective differential output terminals are referred to as v_o^+ and v_o^- .

The average of the output signals measured on terminals V_o^+ and V_o^- is commonly known as the common-mode signal or level, and will be denoted as v_{cm}^{avg} . The desired common-mode signal or level at a terminal V_{cm} will be referred to as v_{cm} and the difference between signals v_{cm}^{avg} and v_{cm} (i.e. $v_{cm}^{avg} - v_{cm}$) will be referred to as the common-mode variation.

In the following discussion, it should be noted that it is typically desired to drive signal v_{cm}^{avg} to be equal to signal v_{cm} during the operation of common-mode circuit **14** so that the difference is zero and, consequently, the common-mode variation is reduced. It is also typically desired to reduce the changes in the common-mode variation when switching from one phase or operational mode to another.

In accordance with the invention, error correcting circuit **22** can be configured to reduce changes in the common-mode variation when switching between phases by balancing the load coupled to terminals V_o^+ and V_o^- and by correcting for charge injection errors. Further, common-mode corrector circuit **18** is configured to compare signal v_{cm}^{avg} with signal v_{cm} and provide a feedback signal v_{FB} at a terminal V_{FB} coupled to circuit **14** where signal v_{FB} is proportional to signal v_{cm}^{avg} . It should be noted that in other embodiments, common-mode corrector circuit **18** can provide a feedforward signal or another signal which is proportional to signal v_{cm}^{avg} and the use of a feedback signal in this embodiment is for illustrative purposes only.

FIG. 2, illustrates a simplified circuit schematic diagram of one embodiment of signal conditioning system **10** illus-

trated in FIG. 1. In this embodiment, common-mode circuit **14** includes n-MOS transistors M_{1a} and M_{1b} connected as a differential amplifier pair. Further, output port **13** is provided by the drains of transistors M_{1a} and M_{1b} , which form differential output terminals V_o^+ and V_o^- . A power source V_{DD} is coupled to transistors M_{1a} and M_{1b} through p-MOS transistors M_{2a} and M_{2b} , respectively. Transistors M_{2a} and M_{2b} each include a control terminal coupled to biasing circuit **16** and provide a biasing current equal to $i_{bias}/2$ to respective transistors M_{1a} and M_{1b} .

A current sinking portion **11** includes a current sinking n-MOS transistor M_0 that sinks a current i_0 from transistors M_{1a} and M_{1b} to current return **12**. Transistor M_0 includes a drain coupled to the sources of transistors M_{1a} and M_{1b} through a terminal V_d and a source connected to a current return **12**. Further, a control terminal of transistor M_0 is connected to common-mode corrector circuit **18** and error correcting circuit **22** at terminal V_{FB} .

It should be noted that current sinking portion **11** can include more than one transistor in some embodiments. This is exemplified in FIG. 2 by current sink **15** which includes parallel n-MOS transistors **17** and **19**. The control terminal of transistor **19** is connected to terminal V_{FB} while the control terminal of transistor **17** is connected to terminal V_{bias} . Current sink **15** can be substituted for current sinking portion **11** as indicated by substitution arrow **21**.

The embodiment with current sink **15** may be desired to adjust the operating characteristics of common-mode circuit **14**. The number of parallel transistors determines the gate capacitance of current sinking portion **11** and the operating frequency of circuit **14**. However, only one transistor is illustrated in current sinking portion **11** for simplicity and ease of discussion.

In accordance with the invention, bias circuit **16** includes a diode connected n-MOS transistor M_3 where the source is coupled to reference potential **12** and the drain is coupled to a current source I_{bias} which provides current i_{bias} . Current source I_{bias} is also coupled to the drain of a diode connected p-MOS transistor M_4 where the source of transistor M_4 is coupled to power supply V_{DD} and the control terminal is coupled to the control terminals of transistors M_{2a} and M_{2b} .

In operation, transistor M_4 is configured to mirror bias current i_{bias} to transistors M_{2a} and M_{2b} . Further, transistor M_3 is configured to provide a bias signal v_{bias} at a terminal V_{bias} connected to a control terminal of transistor M_0 . It should be noted that signal v_{bias} is used to bias transistor M_0 through common-mode corrector circuit **18** and error correcting circuit **22** and, consequently, signal v_{bias} determines the amount of current sunk (i.e. current i_0) by transistor M_0 .

In this embodiment, current return **12** can include a voltage terminal with a reference potential. However, in the embodiment illustrated in FIG. 2, current return **12** is illustrated as a ground terminal (i.e. AC and DC ground), with the potential difference between current return **12** and power supply V_{DD} , connected to the sources of transistors M_{2a} , M_{2b} , and M_4 , driving system **10**.

It should also be noted that above and in the following discussion, the polarity of the various transistors included in system **10** can be changed from n-MOS to p-MOS or from p-MOS to n-MOS. Further, system **10** can include bipolar junction transistors or other types of field effect transistors. Hence, the type and the polarity of the transistors included in system **10** are chosen for simplicity and ease of discussion and are not meant to limit the scope of the invention.

In this embodiment, common-mode corrector circuit **18** includes a switched capacitor network. In particular, common-mode corrector circuit **18** includes a switch M_{10}

5

coupled between terminal V_{bias} and a terminal V_b . Further, terminal V_{cm} is coupled to terminals V_c^+ and V_c^- through switches M_8 and M_9 , respectively.

In accordance with the invention, terminal V_c^- is coupled to terminal V_o^- through a switch M_5 and terminal V_c^+ is coupled to terminal V_o^+ through a switch M_6 . Further, terminal V_b is coupled to terminal V_{FB} through a switch M_7 . A precharging capacitor C_{fly}^a is connected between terminals V_b and V_c^+ and a precharging capacitor C_{fly}^b is connected between terminals V_b and V_c^- . Further, a common-mode feedback capacitor C_{cmfb}^a is connected between terminals V_{FB} and V_o^+ and a common-mode feedback capacitor C_{cmfb}^b is connected between terminals V_{FB} and V_o^- . It should be noted that precharging capacitors C_{fly}^a and C_{fly}^b are often referred to as “flying” capacitors because they are configured to provide charge storage and charge transfer in response to alternating phases or operational modes.

In this embodiment, error correcting circuit **22** includes a switch M_{11} , coupled between common-mode corrector circuit **18** and the control terminal of current sinking transistor M_0 . Circuit **22** further includes a balancing capacitor C_1 and a balancing capacitor C_2 coupled between reference potential **12** and terminals V_b and V_{bias} , respectively. It should be noted that the source and drain of switch M_{11} are connected together so that switch M_{11} is configured to behave as a “dummy” switch, as will be discussed in more detail below.

In some embodiments, at least one of charge balancing capacitors C_1 and C_2 can include a transistor such as a MOS transistor. This realization is exemplified in FIG. 2 by MOS transistors **26** and **32** which are substituted for charge balancing capacitors C_1 and C_2 , respectively, as indicated by respective substitution arrows **28** and **34**.

In this embodiment, switches M_5 through M_{11} include n-MOS transistors with gates coupled to alternately switching clocks. In particular, the gates of switches M_8 , M_9 , M_{10} , and M_{11} are coupled to a clock **1** which provides a clock signal ϕ_1 and the gates of switches M_5 , M_6 , and M_7 are coupled to a clock **2** which provides a clock signal ϕ_2 . It should be noted that clocks **1** and **2** correspond to output signal phases or operational modes which can be provided by phase coupled clock signals. For example, clocks **1** and **2** can provide respective signals ϕ_1 and ϕ_2 which include non-overlapping square clock pulses.

In operation, signal v_{cm}^{avg} is formed by transistors M_{0a} , M_{1a} , M_{1b} , M_{2a} and M_{2b} and is set by the difference between the currents sourced by transistors M_{2a} and M_{2b} (i.e. current i_{bias}) and the current sunk by transistor M_0 (i.e. current i_0). The sum of the currents sourced by M_{2a} and M_{2b} can be different from current i_0 because of processing variations in the various components included in common-mode circuit **102** (i.e. transistors M_{1a} , M_{1b} , M_{2a} , and M_{2b}) and temperature and power supply variations.

Processing variations correspond to chip-to-chip differences that occur when fabricating a large number of chips. It is well known that in a fabrication run some chips will have a higher maximum operating frequency (i.e. a fast process) or a lower maximum operating frequency (i.e. a slow process) than a desired operating frequency because of physical variations (i.e. variations in gate area, film thickness, doping concentration, etc.) in the elements included in system **10**. For example, physical variations can be caused because transistors M_{2a} and M_{2b} are p-MOS transistors which are typically fabricated during a different step from n-MOS transistors M_0 , M_{1a} , M_{1b} , M_3 , and M_4 .

Temperature variations can be caused by the environment surrounding system **10** and power supply variations can include voltage changes in power source V_{DD} . Controlling

6

variations in power source V_{DD} is desirable because circuits are being scaled to lower operating voltages for portable and other applications. For example, in some embodiments power source V_{DD} can be a battery which typically discharges over time. In other embodiments, variations in power source V_{DD} can be from the imperfect regulation of power source V_{DD} in line powered applications.

The balancing of signal v_{cm}^{avg} with signal v_{cm} occurs when common-mode corrector circuit **18** couples output terminals V_o^+ and V_o^- to the gate of current sinking transistor M_0 to adjust a gate bias of transistor M_0 in response to the difference between signals V_{cm}^{avg} and v_{cm} . The coupling is proportional to feedback signal V_{FB} and controls or drives the common-mode signal v_{cm}^{avg} to equal signal V_{cm} .

In operation, when signal ϕ_1 is high and signal ϕ_2 is low (i.e. switches M_8 , M_9 , M_{10} , and M_{11} are on and switches M_5 , M_6 , and M_7 are off), charge proportional to the difference between signals v_{cm} and v_{bias} is stored on capacitors C_{fly}^a and C_{fly}^b . Further, when signal ϕ_1 is low and signal ϕ_2 is high (i.e. switches M_8 , M_9 , M_{10} , and M_{11} are off and switches M_5 , M_6 , and M_7 are on) the charge stored on capacitors C_{fly}^a and C_{fly}^b is transferred to capacitors C_{cmfb}^a and C_{cmfb}^b , respectively. Hence, signals v_{cm}^{avg} and v_{cm} can be compared by alternately clocking the group of switches including M_5 through M_7 and the group of switches including M_8 through M_{11} .

It should also be noted that in this embodiment the gate of switch M_{11} is coupled to clock **1** because common-mode circuit **14** is inactive when signal ϕ_2 is high and signal ϕ_1 is low. In particular, circuit **14** is typically inactive when switches M_5 , M_6 , and M_7 are on because circuit **14** is configured for operation in a switched capacitor environment so that transistors M_{1a} and M_{1b} are active during a system transfer mode when switches M_8 , M_9 , M_{10} , and M_{11} are on. In other embodiments, circuit **14** can be active when either ϕ_1 or ϕ_2 are high to provide amplifier sharing.

An example of the common-mode error gain can be illustrated when signal ϕ_1 is high and signal ϕ_2 is low. If an error signal is sensed (i.e. the common-mode variation is not equal to zero) by the control terminal of transistor M_0 , then there will be a high gain between signal V_{FB} and the common-mode signal at output terminals V_o^+ and V_o^- . The error signal will be scaled by a value that is proportional to the ratio of capacitance $c_{gs}(M_0)$ divided by the sum of capacitances c_{cmfb}^a and c_{cmfb}^b where $c_{gs}(M_0)$ is the total capacitance, including parasitic capacitances, between the control terminal and source of transistor M_0 . However, when signal ϕ_1 is low and signal ϕ_2 is high, the error signal is scaled by a factor proportional to capacitance $c_{gs}^a(M_0)$ divided by the sum of capacitances C_{cmfb}^a , c_{cmfb}^b , C_{fly}^a , and C_{fly}^b .

The change in the common-mode error gain when switching between signals ϕ_1 , and ϕ_2 causes “charge hopping” where signal V_{cm}^{avg} is a function of both signals ϕ_1 and ϕ_2 . Hence, the common-mode error gain depends on parasitic capacitances and the common-mode variations caused by phase-to-phase gain variations depend on capacitances C_{fly}^a and C_{fly}^b .

Charge injection errors can be caused by currents flowing through parasitic capacitances of the transistors and switches included in system **10**. Charge injection errors can also be caused by changes in the channel charge under a transistor gate as the transistor switches between the off and on state. It should be noted that the parasitic capacitances allow a control signal at a control terminal or gate of a transistor to be coupled to a corresponding transistor source or drain, the coupling resulting in a parasitic charge or current flow. The

control signal coupling is referred to as feedthrough and occurs when charge is injected between the gate and the source or drain.

The parasitic capacitances illustrated in FIG. 2 are shown in phantom by indicating the relevant component with broken lines. For example, switch M_7 has a parasitic gate to drain capacitance c_{gd7} with an injected charge q_{gd7} and a parasitic gate to source capacitance c_{gs7} with an injected charge q_{gs7} . Further, switch M_{10} has a parasitic gate to drain capacitance c_{gd10} with an injected charge q_{gd10} and a parasitic gate to source capacitance c_{gs10} with an injected charge q_{gs10} . Switch M_{11} , has a parasitic gate to drain capacitance c_{gd11} with an injected charge q_{gd11} and a parasitic gate to source capacitance c_{gs11} with an injected charge q_{gs11} and transistor M_3 has parasitic gate capacitance $c_{gs}(M_3)$. It should be noted that the injected charge corresponds to electrons where it is conventional to define positive current flow to be in a direction opposite to the direction of electron flow.

If capacitors C_1 and C_2 are excluded from system 10, then the impedance to reference potential 12 for terminals V_b , V_{FB} , and V_{bias} , will depend on the impedances through parasitic capacitors $C_{gs}(M_0)$, $C_{gs}(M_3)$, C_{gs7} , C_{gd7} , C_{gd10} , and C_{gs10} . By including capacitors C_1 and C_2 in system 10, however, the impedance to reference potential 12 for terminals V_b , V_{FB} , and V_{bias} will depend more on the impedances through capacitors C_1 and C_2 and less on the parasitic impedances and, consequently, will be more constant as a function of time.

In accordance with the invention, the common-mode error gain and the charge injection errors can be minimized by configuring common-mode error correcting circuit 22. In particular, capacitances c_1 and c_2 can be chosen to reduce the charge injection error and the variations in the common-mode error gain by setting the impedance to reference potential 12 for terminals V_{FB} , V_b , and V_{bias} to a desired value. Further, switch M_{11} can be configured to reduce the charge injection error by selecting capacitances c_{gs11} and c_{gd11} so that the charge injection is balanced between MO and common-mode corrector circuit 18.

In this embodiment, switch M_{11} is configured by choosing its gate area to be proportional to the gate area of switch M_7 . For example, when switch M_{11} is "half-sized", then its gate area is one-half the size of the gate area of switch M_7 . Similarly, when switch M_{11} is "full sized", then its gate area is equal to the gate area of switch M_7 and when switch M_{11} is "three-quarters sized", then its gate area is three-quarters the size of the gate area of switch M_7 .

Capacitors C_1 and C_2 provide impedance matching between terminals V_b and V_{Bias} and adjacent terminals such as terminal V_{FB} . Hence, capacitances c_1 and c_2 can be chosen to match an impedance of terminal V_b to an impedance of terminal V_{bias} when switching between signals ϕ_1 and ϕ_2 . When terminals V_b and V_{bias} are impedance matched with the rest of system 10, an equal or balanced charge is transferred between terminals V_b and V_{bias} and each adjacent terminal when clocking switches M_5 through M_{11} .

When choosing capacitances c_1 and c_2 , the common-mode error gain when signal ϕ_1 is high is proportional to capacitance $c_{gs}(M_0)$ divided by the sum of capacitances c_{cmfb}^a and c_{cmfb}^b . Further, the common-mode error gain when signal ϕ_2 is high is proportional to the sum of capacitances $c_{gs}(M_0)$ and c_1 , divided by the sum of capacitances c_{cmfb}^a , c_{cmfb}^b , c_{fly}^a , and c_{fly}^b . Thus, for the common-mode error gain to

remain constant, the error gain when signal ϕ_1 is high should be equal to the error gain when signal ϕ_2 is high so that:

$$\frac{c_{gs}(M_0)}{(c_{cmfb}^a + c_{cmfb}^b)} = \frac{(c_{gs}(M_0) + c_1)}{(c_{cmfb}^a + c_{cmfb}^b + c_{fly}^a + c_{fly}^b)} \quad (1)$$

A solution to Equation (1) can be obtained when capacitances $c_{gs}(M_0)$ and c_1 are equal and when capacitance c_{cmfb}^a equals capacitance c_{fly}^a and capacitance c_{cmfb}^b equals capacitance c_{fly}^b so that:

$$\frac{c_{gs}(M_0)}{(c_{cmfb}^a + c_{cmfb}^b)} = \frac{2c_1}{2(c_{fly}^a + c_{fly}^b)} = \frac{c_1}{(c_{fly}^a + c_{fly}^b)} \quad (2)$$

It should be noted that in some embodiments without capacitance c_1 in Equation (1), capacitances c_{fly}^a and c_{fly}^b would need to be smaller in order to decrease the common-mode variations when switching between signals ϕ_1 and ϕ_2 . For example, in some designs, capacitances c_{fly}^a and c_{fly}^b are chosen to be equal to capacitances $c_{cmfb}^a/10$ and $c_{cmfb}^b/10$, respectively. However, when capacitances c_{fly}^a and c_{fly}^b are made smaller it takes more time to correct for the common-mode variation because it will take more clock cycles to move charge from terminals V_{cm} and V_{bias} to capacitors C_{cmfb}^a and C_{cmfb}^b . Hence, it is desirable to increase capacitances C_{fly}^a and C_{fly}^b to increase the charge transfer rate from terminals V_{cm} and V_{bias} to capacitors C_{cmfb}^a and C_{cmfb}^b so that it takes less time (i.e. fewer clock cycles) to drive signal V_{cm}^{avg} to V_{cm} .

FIG. 3 illustrates a graph 50 of signal v_{cm}^{avg} of system 10 versus time for two different values of capacitances c_{fly}^a and c_{fly}^b . A curve 52 corresponds to the case where capacitances $c_{fly}^a = c_{cmfb}^a/10$, $c_{fly}^b = c_{cmfb}^b/10$, and $c_{gs}(M_0) = c_1$ and a curve 54 corresponds to the case where capacitances $c_{fly}^a = c_{cmfb}^a$, $c_{fly}^b = c_{cmfb}^b$ and $c_{gs}(M_0) = c_1$. Also shown in FIG. 3 is a curve 42 that corresponds to a steady-state condition in which system 10 does not include capacitors c_1 and c_2 or switch M_{11} and capacitances $c_{fly}^a = c_{cmfb}^a/10$ and $c_{fly}^b = c_{cmfb}^b/10$. In this example, the desired common-mode signal v_{cm} is 850 mV or 0.850 volts, although signal v_{cm} can be chosen to be another desired value.

As shown in FIG. 3, the common-mode signal can be corrected to the desired common-mode signal faster when capacitances c_{fly}^a and c_{fly}^b are larger (i.e. curve 54) because curve 54 converges to curve 42 quicker than curve 52. Hence, capacitors C_{fly}^a and C_{fly}^b can transfer more charge in a given time from terminal V_{cm} to capacitors C_{cmfb}^a and C_{cmfb}^b , respectively.

Hence, one advantage of using capacitor C_1 is that capacitances c_{fly}^a and c_{fly}^b can be increased by choosing a value for capacitor C_1 so that Equation (2) is satisfied. For example, capacitances c_{fly}^a and c_{fly}^b can be made equal to capacitances c_{cmfb}^a and c_{cmfb}^b , respectively, and capacitance $c_g(M_0)$ can be equal to capacitance c_1 .

It is anticipated that capacitance c_{fly}^a can be within a range between one half to one times a capacitance of c_{cmfb}^a and that capacitance c_{fly}^b can be within a range between one half to one times a capacitance c_{cmfb}^b to minimize common-mode variations and to maximize the charge transfer rate. It should be noted, however, that capacitances c_{fly}^a and c_{fly}^b can have values outside these ranges in other embodiments.

Capacitances c_1 and c_2 can be chosen to balance the parasitic currents injected by switches M_7 and M_{10} and

transistors M_0 and M_3 to minimize the charge injection errors. As an example, if bias circuit **16** has a medium impedance through capacitor c_{gs} (M_3) common-mode circuit **14** has a low impedance through capacitor c_{gs} (M_0), and terminal V_b has a high impedance to current return **12**, then charges will preferentially flow towards terminal V_{bias} when signal ϕ_1 goes high and signal ϕ_2 goes low.

Hence, when signal ϕ_1 goes low and signal ϕ_2 goes high, the magnitude of charge q_{gs11} will be equal to charge q_{gd11} because the source and drain of switch M_{11} are connected together (i.e. switch M_{11} is a dummy switch). The magnitude of charge q_{gd7} will be greater than charge q_{gs7} and the magnitude of charge q_{gd10} will be less than charge q_{gs10} . Charge q_{gd7} can be made equal to $q_{gs11} + q_{gd11}$ by sizing switch M_{11} to have an area and width equal to one-half of the area and width of switch M_7 and by choosing the impedance between reference potential **12** and terminals V_{FB} and V_b to be equal. The relative magnitudes of the injected charges are indicated by the size of the arrows representing the corresponding charges. Further, the directions of the arrows indicate that most of the charge flow will be towards terminal V_{bias} .

As another example, if signal ϕ_1 goes low and signal ϕ_2 goes high, then the magnitude of charge q_{gs11} will be equal to charge q_{gd11} , the magnitude of charge q_{gd7} will be greater than charge q_{gs7} , and the magnitude of charge q_{gd10} will be less than charge q_{gs10} . Further, the direction of the corresponding arrows will be the opposite as that indicated in FIG. **2** because most of the charge will flow away from terminal V_{bias} .

If terminal V_{bias} has the same impedance through capacitor c_{gs} (M_3) as capacitor c_{gs} (M_0), however, then the magnitudes of the injected charge flow will be the same through the parasitic capacitances because the impedances will be equal or balanced. Hence, the size of the arrows representing the charge flow will be equal.

The charge or current balancing of the injected charges provides less common-mode variations and gain errors. To provide minimal common-mode gain and charge injection errors, it is anticipated that capacitances c_1 and c_{gs} (M_0) can be equal so that the injected charge is balanced or split evenly between terminals V_b and V_{FB} . It is also anticipated that the sum of capacitances c_{gs} (M_3) and c_2 can be equal to capacitance c_{gs} (M_0) so that charge is balanced or split evenly between terminals V_b and V_{bias} .

The common-mode variation can be illustrated by considering the following examples. It should be noted that in these examples, the desired common-mode level v_{cm} is equal to 850 mV and the graphs show the value of signal v_{cm}^{avg} as a function of time or clock signals ϕ_1 and ϕ_2 . In the following examples, it is typically desired to have signal v_{cm}^{avg} equal to signal v_{cm} and to have signal v_{cm}^{avg} be the same when switching between clocks **1** and **2**.

If signal v_{cm}^{avg} is the same when switching between clocks **1** and **2**, then V_{cm}^{avg} when clock **1** is high (i.e. $v_{cm}^{avg}(\phi_1)$) will be equal to v_{cm}^{avg} when clock **2** is high (i.e. $v_{cm}^{avg}(\phi_2)$). Hence, a measure of the common-mode variations and the error gain for various configurations of error correcting circuit **22** can be determined by comparing the difference and the average of signals $v_{cm}^{avg}(\phi_1)$ and $v_{cm}^{avg}(\phi_2)$ where, in these examples, the average should be 850 mV.

FIG. **4** illustrates a graph **40** of signal v_{cm}^{avg} of system **10** verses clock signals ϕ_1 and ϕ_2 . In FIG. **4**, curve **42** corresponds to signal v_{cm}^{avg} without balancing capacitors C_1 and C_2 or switch M_{11} . A curve **44** corresponds to signal v_{cm}^{avg} with capacitor C_2 and without both capacitor C_1 and switch M_{11} . A curve **46** corresponds to signal v_{cm}^{avg} with capacitor C_1 and without both capacitor C_2 and switch M_{11} . A curve **48** corresponds to signal v_{cm}^{avg} with both capacitors C_1 and C_2 and without switch M_{11} .

The common-mode variation and the average variation between clock signals ϕ_1 and ϕ_1 for curves **42**, **44**, **46**, and **48** are shown in Table 1. It can be seen from Table 1 and graph **40** that capacitances c_1 and c_2 shift curve **42** towards the desired common-mode signal v_{cm} (i.e. 850 mV) where capacitor C_1 has slightly more of an affect than capacitor C_2 because it is shifted closer to 850 mV. When capacitors C_1 and C_2 are both included, the common-mode level is shifted even closer to 850 mV. Hence, capacitors C_1 and C_2 can reduce the difference between $v_{cm}^{avg}(\phi_1)$ and $v_{cm}^{avg}(\phi_2)$ and move the average of signals $v_{cm}^{avg}(\phi_1)$ and $v_{cm}^{avg}(\phi_2)$ closer to 850 mV.

TABLE 1

Common-mode variations for graph 40.					
Graph 40	$v_{cm}^{avg}(\phi_1)$	$v_{cm}^{avg}(\phi_2)$	$v_{cm}^{avg}(\phi_1) - v_{cm}^{avg}(\phi_2)$	$\frac{v_{cm}^{avg}(\phi_1) + v_{cm}^{avg}(\phi_2)}{2}$	
Curve 42	897 mV	863 mV	350 mV	880 mV	
Curve 44	C_2	896 mV	861 mV	350 mV	879 mV
Curve 46	C_1	875 mV	853 mV	220 mV	864 mV
Curve 48	C_1, C_2	873 mV	851 mV	220 mV	862 mV

FIG. **5** illustrates a graph **60** of signal v_{cm}^{avg} of system **10** verses clock signals ϕ_1 and ϕ_2 . In FIG. **5**, a curve **62** corresponds to signal v_{cm}^{avg} with a half-sized switch M_{11} , a curve **64** corresponds to signal v_{cm}^{avg} with a full-sized switch M_{11} , and a curve **66** corresponds to signal v_{cm}^{avg} with a three-quarters sized switch M_{11} . It should be noted that capacitors C_1 and C_2 are not included in system **10** for the curves in FIG. **5** to illustrate the effects of switch M_{11} .

The common-mode variation and the average variation between clocks ϕ_1 and ϕ_1 for curves **42**, **62**, **64**, and **66** are shown in Table 2. It can be seen from Table 2 and graph **62** that adding switch M_{11} shifts curve **42** toward the desired common-mode signal v_{cm} (i.e. 850 mV) and decreases the common-mode gain errors (i.e. $v_{cm}^{avg}(\phi_1) - v_{cm}^{avg}(\phi_2)$) between clocks ϕ_1 and ϕ_2 . As the area of switch M_{11} in increased to a three-quarters sized switch, signal $v_{cm}^{avg}(\phi_1)$ approaches $v_{cm}^{avg}(\phi_2)$. For a full-sized switch, $v_{cm}^{avg}(\phi_1)$ becomes less than $v_{cm}^{avg}(\phi_2)$ indicating that the optimum size in some embodiments is between a three-quarters sized switch and a full-sized switch. Hence, when switch M_{11} , is three-quarters sized, the common-mode gain error is less than the full-sized and half-sized cases (see curve **66**). Thus, by optimizing the size of switch M_{11} , the difference between

$v_{cm}^{avg}(\phi_1)$ and $v_{cm}^{avg}(\phi_2)$ can be reduced and the average of signals $v_{cm}^{avg}(\phi_1)$ and $v_{cm}^{avg}(\phi_2)$ can be moved closer to 850 mV.

without significantly degrading the performance. One cause of performance degradation is an increased variation in the common-mode levels.

TABLE 2

Common-mode variations for graph 60.				
Graph 60	$v_{cm}^{avg}(\phi_1)$	$v_{cm}^{avg}(\phi_2)$	$v_{cm}^{avg}(\phi_1) - v_{cm}^{avg}(\phi_2)$	$\frac{v_{cm}^{avg}(\phi_1) + v_{cm}^{avg}(\phi_2)}{2}$
Curve 42	897 mV	863 mV	350 mV	880 mV
Curve 62 Half size	874 mV	861 mV	13 mV	868 mV
Curve 64 Full size	847 mV	858 mV	-11 mV	853 mV
Curve 66 3/4 size	862 mV	860 mV	2 mV	861 mV

In a typical manufacturing process, a circuit can be fabricated on a large number of individual substrates. It is well known that variations in the performance of the circuit can occur from one substrate to another where, in general, the variations are caused by variations in the semiconductor processing. For example, a particular film, such as an oxide or a conductive material, can be thicker on one substrate compared to another. The doping density can also vary throughout the manufacturing process which can affect the number of carriers in a particular region.

Hence, processing variations can cause differences in the performance of system **10** when manufacturing copies of it on the same or separate substrates. For example, when testing a large number of circuits, an average or nominal performance will be obtained where some circuits can run at a higher maximum possible frequency and others can run at a lower maximum possible frequency. The performance can affect the values of the common-mode level and variation. The performance can also affect the range of values for the common-mode level and variation.

It is desired to have the common-mode level and variation constant from one circuit to another when fabricating a large number of circuits. It is also desired to have the range of values for the common-mode level and variation narrow so that the performance of each individual circuit will be approximately the same for all conditions.

The differences in performance due to processing variations can be represented by simulating system **10** using a "fast model" or a "slow model". The fast model represents the performance of system **10** when system **10** has been subject to processing variations that lead to a higher maximum possible operating frequency. The slow model represents the performance of system **10** when system **10** has been subject to processing variations that lead to a lower maximum possible operating frequency. It is generally desired to be able to operate system **10** at both high and low temperatures

For this discussion, an operating temperature range between 125° C. and -40° C. is used as a benchmark where 125° C. is the expected highest operating temperature of system **10** and -40° C. is the expected lowest operating temperature. A temperature of 55° C. is used as the nominal temperature which represents the expected average operating temperature of system **10**. It should be noted that these temperatures are chosen for illustrative purposes only and are not meant to limit the scope of the invention.

It should also be noted that in one embodiment, system **10** is fabricated with silicon-based circuitry. However, system **10** can be fabricated using other material systems. Examples of other material systems include III-V semiconductor materials, such as gallium arsenide, gallium nitride, or aluminum nitride. Other examples include germanium, silicon germanium, or silicon carbide.

FIG. **6** illustrates a graph **80** showing the effects of processing, power supply, and temperature variations for system **10** where capacitors C_1 and C_2 are excluded and switch $M_{1,1}$, is three-quarters sized.

In FIG. **6**, a curve **82** corresponds to a fast process at a temperature of 125° C. where $V_{DD}=2$ volts. A curve **84** corresponds to the nominal process at a temperature of 55° C. where $V_{DD}=1.8$ volts and a curve **86** corresponds to a slow process at a temperature of -40° C. where $V_{DD}=1.6$ volts.

Curves **86** and **82** are chosen to represent the best and worst case responses, respectively, over process, power, and temperature variations and graph **84** represents the typical response under nominal or normal operating conditions.

For curve **86**, the difference between signals $v_{cm}^{avg}(\phi_1)$ and $v_{cm}^{avg}(\phi_2)$ is about -2 mV and the average is around 849 mV. For curve **82**, the difference between signals $v_{cm}^{avg}(\phi_2)$ and $v_{cm}^{avg}(\phi_1)$ is about 10 mV and the average is around 883 mV. For curve **84**, the difference between signals $v_{cm}^{avg}(\phi_1)$ and $v_{cm}^{avg}(\phi_2)$ is about 1 mV and the average is around 862 mV.

TABLE 3

Common-mode variations for graph 80.				
Graph 80	$v_{cm}^{avg}(\phi_1)$	$v_{cm}^{avg}(\phi_2)$	$v_{cm}^{avg}(\phi_1) - v_{cm}^{avg}(\phi_2)$	$\frac{v_{cm}^{avg}(\phi_1) + v_{cm}^{avg}(\phi_2)}{2}$
Curve 42	897 mV	863 mV	350 mV	880 mV
Curve 82 Fast	888 mV	878 mV	10 mV	883 mV
Curve 84 Nom.	862 mV	861 mV	1 mV	862 mV
Curve 86 Slow	848 mV	850 mV	-2 mV	849 mV

The common-mode variations and the average variation between clock signals ϕ_1 and ϕ_2 for curves **42**, **82**, **84**, and **86** are shown in Table 3. It can be seen from Table 3 and graph **80** that the average of v_{cm}^{avg} for clock signals ϕ_1 and ϕ_2 is expected to be in a range from 883 mV to 849 mV when fabricating a large number of circuits. Further, when fabricating a large number of circuits, the difference between $v_{cm}^{avg}(\phi_1)$ and $v_{cm}^{avg}(\phi_2)$ is expected to be in a range from -2 mV to 10 mV.

FIG. 7 illustrates a graph **70** of signal v_{cm}^{avg} of system **10** versus clock signals ϕ_1 and ϕ_2 when system **10** includes capacitors C_1 and C_2 and switch M_{11} , where switch M_{11} , is one-half sized. A curve **72** corresponds to a fast process at a temperature of 125° C. where $V_{DD}=2$ volts. A curve **74** corresponds to the nominal process at a temperature of 55° C. where $V_{DD}=1.8$ volts. A curve **76** corresponds to a slow process at a temperature of -30° C. where $V_{DD}=1.6$ volts.

TABLE 4

Common-mode variations for graph 70.				
Graph 70	$v_{cm}^{avg}(\phi_1)$	$v_{cm}^{avg}(\phi_2)$	$v_{cm}^{avg}(\phi_1) - v_{cm}^{avg}(\phi_2)$	$\frac{v_{cm}^{avg}(\phi_1) + v_{cm}^{avg}(\phi_2)}{2}$
Curve 42	897 mV	863 mV	350 mV	880 mV
Curve 72 Fast	858 mV	851 mV	7 mV	855 mV
Curve 74 Nom.	852 mV	845 mV	7 mV	849 mV
Curve 76 Slow	844 mV	842 mV	2 mV	843 mV

The common-mode variation and the average common-mode variation between clock signals ϕ_1 and ϕ_2 for curves **42**, **72**, **74**, and **76** are shown in Table 4. The values in Table 4 can be compared to the values in Table 3 to illustrate the improvement in the difference and the average of $v_{cm}^{avg}(\phi_1)$ and $v_{cm}^{avg}(\phi_2)$ when switching between clock signals ϕ_1 and ϕ_2 . It can be seen from Table 4 and graph **70** that the average of v_{cm}^{avg} for clock signals ϕ_1 and ϕ_2 is expected to be in a range from 855 mV to 843 mV when fabricating a large number of circuits. Further, when fabricating a large number of circuits, the difference between $v_{cm}^{avg}(\phi_1)$ and $v_{cm}^{avg}(\phi_2)$ is expected to be in a range from 2 mV to 7 mV.

Hence, by optimizing the area of switch M_{11} , and by including capacitors C_1 and C_2 , the average of $v_{cm}^{avg}(\phi_1)$ and $v_{cm}^{avg}(\phi_2)$ can be closer to the desired value of 850 mV when fabricating a large number of circuits. Further, the difference between $v_{cm}^{avg}(\phi_1)$ and $v_{cm}^{avg}(\phi_2)$ can be significantly reduced. Thus, the effects of processing variations commonly found in the manufacturing process can be minimized so that each circuit will have a similar performance.

Thus, a circuit with a common-mode dual output has been disclosed. The circuit can include a common-mode circuit with an output portion coupled to a common-mode corrector circuit. An error correcting circuit is connected to the common-mode corrector circuit to improve the performance.

The error correcting circuit can include capacitors C_1 and C_2 and switch M_{11} which can be configured to reduce variations in the common-mode level of the circuit when switching between two operational modes. Capacitors C_1 and C_2 and switch M_{11} can also be configured to reduce the range of values for the common-mode level and variation when fabricating a large number of circuits. Further, by including capacitor C_1 , capacitor C_{fly} can be made larger so that the common-mode level can be corrected to the desired common-mode level with fewer clock cycles.

The embodiments of the invention described herein are exemplary and numerous modifications, variations and rearrangements can be readily envisioned to achieve substantially equivalent results, all of which are intended to be embraced within the spirit and scope of the invention as defined in the appended claims.

What is claimed is:

1. A circuit with a common-mode dual output comprising:
 - a common-mode circuit with an output portion;
 - a common-mode corrector circuit connected to alternate the states of said output portion between an average output level and a desired common-mode level, the difference between the average and desired levels being proportional to a signal offset level; and
 - an error correcting circuit connected to said common-mode corrector circuit to adjust the signal offset level;

wherein said common-mode corrector circuit further includes:

- a common-mode voltage terminal connected to said output portion through a first pair of switches, said first pair of switches being responsive to alternating clock cycles which alternate the states of said output portion;
- a bias terminal providing a bias level, said bias terminal being connected to a first control terminal in said common-mode circuit through a second pair of switches, said second pair of switches being responsive to the alternating clock cycles;
- a precharging capacitor which stores the difference between the desired common-mode level and the bias level during a first clock cycle in the alternating clock cycles; and
- a common-mode capacitor which stores the average output level during the first clock cycle, said common-mode capacitor and said precharging capacitor being connected in parallel during a second clock cycle in the alternating clock cycles.

2. The circuit of claim 1, wherein said error correcting circuit includes a first capacitor coupled to said common-mode corrector circuit to reduce the difference between the average and desired levels.

3. The circuit of claim 2, wherein said first capacitor provides impedance matching to said bias terminal and control terminal during the first and second clock cycles, respectively.

4. The circuit of claim 1, wherein said error correcting circuit includes a second capacitor coupled to said bias terminal to reduce the difference between the average and desired levels.

5. The circuit of claim 2, wherein said error correcting circuit is configured to impedance match said bias terminal and control terminal with a terminal of said precharging capacitor.

15

6. The circuit of claim 1, wherein a capacitance of said precharging capacitor is chosen to be proportional to a capacitance of said first capacitor.

7. The circuit of claim 1, wherein said error correcting circuit includes a switch configured to reduce charge injection between said common-mode circuit and said common-mode corrector circuit.

8. The circuit of claim 1, wherein:
 said precharging capacitor is coupled to said output portion; and
 said common-mode circuit includes a differential amplifier pair of transistors and a current sinking transistor that includes said bias terminal and that sinks a current from said transistors.

9. The circuit of claim 8, wherein said error correcting circuit includes a transistor switch coupled between said bias terminal and said precharging capacitor to reduce charge injection errors during said first clock cycle.

10. The circuit of claim 1, wherein said error correcting circuit includes a first capacitor coupled to said precharging capacitor and to said common-mode capacitor to reduce the difference between the average and desired levels.

11. An integrated circuit, comprising:
 a differential amplifier circuit with an output portion and a current sinking portion, said output portion including dual outputs which provide an average output level;
 a common-mode feedback circuit coupled to said output portion, said feedback circuit providing a desired common-mode level in a first operational mode and generating a feedback signal proportional to the difference between the average output level and the desired common-mode level in a second operational mode, the feedback signal being coupled to said current sinking portion; and

an impedance matching circuit connected to said feedback circuit to adjust the feedback signal;
 wherein the desired common-mode signal is provided to a precharging capacitor in the first operational mode, said precharging capacitor including a terminal coupled to said impedance matching circuit.

12. The integrated circuit of claim 11, wherein said impedance matching circuit is configured to reduce charge injection in said terminal when switching between the first and second operational modes.

13. The integrated circuit of claim 12, wherein said terminal is coupled to a bias terminal during the first operational mode and is coupled to said current sinking portion during the second operational mode.

14. The integrated circuit of claim 13, wherein said impedance matching circuit is configured to impedance match said terminal with at least one of said bias terminal and said current sinking portion when switching between the first and second operational modes, respectively.

15. The integrated circuit of claim 14, further including a switch configured to provide charge balancing between said current sinking portion and said feedback circuit.

16. The integrated circuit of claim 15, wherein an area of said switch is chosen to obtain a desired charge injection level through said switch.

17. The integrated circuit of claim 15, wherein said switch includes a field effect transistor with a control terminal coupled with the first operational mode.

18. A switched capacitor amplifier which provides an output signal in response to an input signal and corrects the

16

average output level of the output signal in accordance with a desired common-mode level, said amplifier comprising:

a differential amplifier with an output portion and a current sinking portion, said output portion providing the output signal;

a switched capacitor common-mode feedback circuit coupled between said output portion and said current sinking portion, said feedback circuit being configured to alternate the states of said output portion between the average output level on a precharging capacitor and the desired common-mode level on a commonmode feedback capacitor in response to alternating clock cycles, the difference between the average and desired levels being proportional to a signal offset level;

an impedance matching circuit coupled to said feedback circuit to adjust the signal offset level, said impedance matching circuit including a charge balancing switch configured to reduce feedthrough between said differential amplifier and said feedback circuit.

19. The amplifier of claim 18, wherein said precharging capacitor is connected in parallel to said common-mode feedback capacitor during one cycle in the alternating clock cycles.

20. The amplifier of claim 18, wherein said impedance matching circuit includes a first capacitor configured to reduce a common-mode gain error in said differential amplifier.

21. The amplifier of claim 18, wherein a capacitance of said precharging capacitor is chosen to be in a range from one-half to one times a capacitance of said common-mode feedback capacitor.

22. The amplifier of claim 18, wherein said charge balancing switch includes a field effect transistor with a gate capacitance chosen to provide a desired feedthrough current.

23. The amplifier of claim 18, wherein a capacitance of said charge balancing switch is proportional to a desired charge injection level between said current sinking portion and said feedback circuit.

24. The amplifier of claim 18, wherein said impedance matching circuit includes a first capacitor coupled to a terminal of said precharging capacitor.

25. The amplifier of claim 24, wherein said first capacitor provides a balanced charge transfer between said terminal and a bias terminal during a first clock, cycle in the alternating clock cycles.

26. The amplifier of claim 25, wherein said first capacitor provides a balanced charge transfer between said terminal and said current sinking portion during a second clock cycle in the alternating clock cycles.

27. The amplifier of claim 26, wherein said impedance matching circuit includes a second capacitor coupled to said bias terminal, said second capacitor providing a balanced charge transfer between said bias terminal and said terminal when switching between the first and second clock cycles.

28. The amplifier of claim 27, wherein said second capacitor has a capacitance proportional to the sum of a capacitance of said current sinking portion and a capacitance of a bias circuit connected to said bias terminal.

29. The integrated circuit of claim 11, wherein said current sinking portion responds to the feedback signal to adjust the average output signal.